

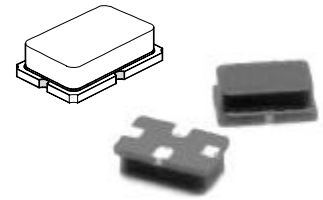


**RO2134A**

- **Very Low Series Resistance**
- **Quartz Stability**
- **Surface-Mount, Ceramic Case with 21 mm<sup>2</sup> Footprint**
- **Complies with Directive 2002/95/EC (RoHS)**

**372.5 MHz  
SAW  
Resonator**

The RO2134A is a one-port, surface-acoustic-wave (SAW) resonator in a surface-mount ceramic case. It provides reliable, fundamental-mode stabilization of fixed-frequency transmitters operating at 372.5 MHz.



**SM-2 Case**

**Absolute Maximum Ratings**

Rating	Value	Units
CW RF Power Dissipation	+10	dBm
DC Voltage Between Terminals (Observe ESD Precautions)	±30	VDC
Case Temperature	-40 to +85	°C
Soldering Temperature (10 seconds / 5 cycles MAX.)	+260	°C

**Electrical Characteristics**

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Center Frequency at +25 °C Absolute Frequency	$f_C$	2, 3, 4, 5		372.5		MHz
	$\Delta f_C$				±100	kHz
Insertion Loss	IL	2		0.9	2.2	dB
Quality Factor	$Q_U$	5, 6, 7		16,100		
	$Q_L$			1,700		
Temperature Stability	$T_O$	6, 7, 8	10	25	40	°C
	$f_O$			$f_C$		
	FTC			0.032		ppm/°C <sup>2</sup>
Frequency Aging	fA	1		≤10	50	ppm/yr
DC Insulation Resistance between Any Two Terminals		5	1.0			MΩ
RF Equivalent RLC Model	$R_M$	5, 7, 9		11.525	29	Ω
	$L_M$			79.074		μH
	$C_M$			2.31		fF
	$C_P$		5, 6, 9		2.34	
Test Fixture Shunt Inductance	$L_{TEST}$	2, 3		76.39		nH
Lid Symbolization (in Addition to Lot and/or Date Code)	131					



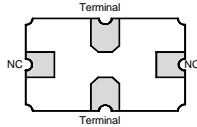
**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**Notes:**

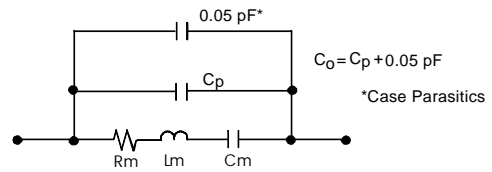
- Lifetime (10 year) frequency aging.
- The center frequency,  $f_C$ , is measured at the minimum insertion loss point,  $IL_{MIN}$ , with the resonator in the 50 Ω test system (VSWR ≤ 1.2:1). The shunt inductance,  $L_{TEST}$ , is tuned for parallel resonance with  $C_O$  at  $f_C$ .
- One or more of the following United States patents apply: 4,454,488 and 4,616,197.
- Typically, equipment utilizing this device requires emissions testing and government approval, which is the responsibility of the equipment manufacturer. Unless noted otherwise, case temperature  $T_C = +25°C ± 2°C$ .
- The design, manufacturing process, and specifications of this device are subject to change without notice.
- Derived mathematically from one or more of the following directly measured parameters:  $f_C$ , IL, 3 dB bandwidth,  $f_C$  versus  $T_C$ , and  $C_O$ .
- Turnover temperature,  $T_O$ , is the temperature of maximum (or turnover) frequency,  $f_O$ . The nominal frequency at any case temperature,  $T_C$ , may be calculated from:  $f = f_O [1 - FTC (T_O - T_C)^2]$ .
- This equivalent RLC model approximates resonator performance near the resonant frequency and is provided for reference only. The capacitance  $C_O$  is the static (nonmotional) capacitance between the two terminals measured at low frequency (10 MHz) with a capacitance meter. The measurement includes parasitic capacitance with "NC" pads unconnected. Case parasitic capacitance is approximately 0.05 pF. Transducer parallel capacitance can be calculated as:  $C_P = C_O - 0.05 \text{ pF}$ .

## Electrical Connections

The SAW resonator is bidirectional and may be installed with either orientation. The two terminals are interchangeable and unnumbered. The callout NC indicates no internal connection. The NC pads assist with mechanical positioning and stability. External grounding of the NC pads is recommended to help reduce parasitic capacitance in the circuit.

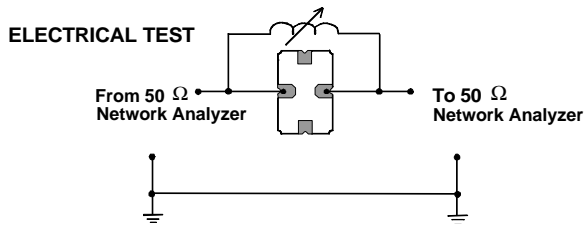


## Equivalent LC Model

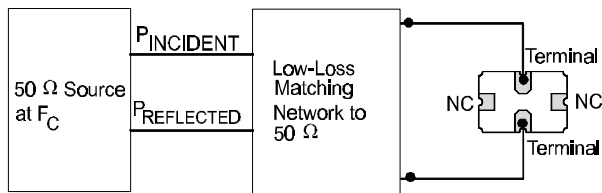


## Typical Test Circuit

The test circuit inductor,  $L_{TEST}$ , is tuned to resonate with the static capacitance,  $C_0$ , at  $F_C$ .



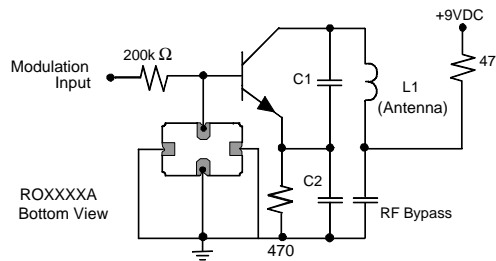
## POWER TEST



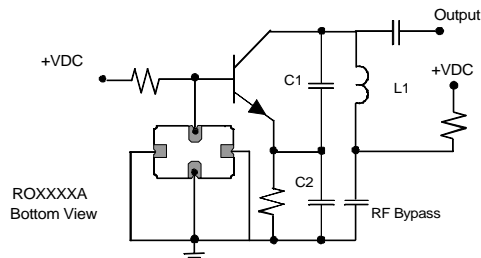
$$CW\ RF\ Power\ Dissipation = P_{INCIDENT} - P_{REFLECTED}$$

## Typical Application Circuits

### Typical Low-Power Transmitter Application

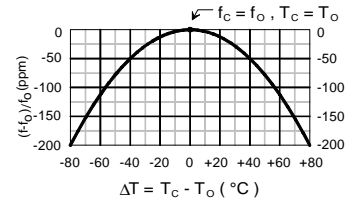


### Typical Local Oscillator Application



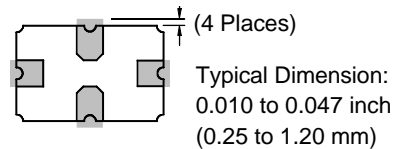
## Temperature Characteristics

The curve shown on the right accounts for resonator contribution only and does not include LC component temperature contributions.



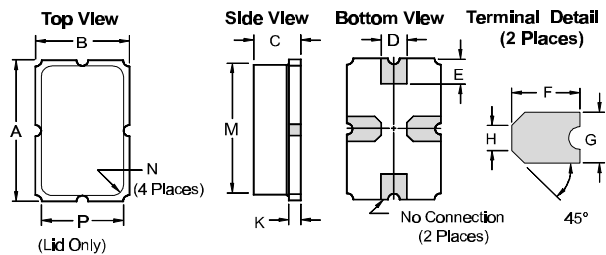
## Typical Circuit Board Land Pattern

The circuit board land pattern shown below is one possible design. The optimum land pattern is dependent on the circuit board assembly process which varies by manufacturer. The distance between adjacent land edges should be at a maximum to minimize parasitic capacitance. Trace lengths from terminal lands to other components should be short and wide to minimize parasitic series inductances.



## Case Design

The case material is black alumina with contrasting symbolization. All pads are nominally centered with respect to the base and consist of 40 to 70 microns (min) electroless gold on 60-350 microns (min) electroless nickel.



Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	5.74	5.99	0.226	0.236
B	3.73	3.99	0.147	0.157
C	1.91	2.16	0.075	0.085
D	0.94	1.10	0.037	0.043
E	0.83	1.20	0.033	0.047
F	1.16	1.53	0.046	0.060
G	0.94	1.10	0.037	0.043
H	0.43	0.59	0.017	0.023
K	0.43	0.59	0.017	0.023
M	5.08	5.33	0.200	0.210
N	0.38	0.64	0.015	0.025
P	3.05	3.30	0.120	0.130